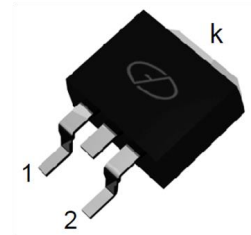


Features

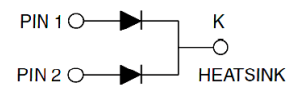
- FRED (Planar) wafer construction
- Low forward voltage drop, low power loss
- High efficiency
- Plastic package has underwriters Laboratory
Flammability Classification 94V-0



Package: TO-263

Mechanical Data

- Case: Epoxy, Molded
- Weight: 1.4grams (approximately)
- Finish: all external surfaces corrosion resistant and terminal leads are readily solderable
- Lead temperature for soldering purposes: 260°C max. for 10 sec
- Shipped 50 units per plastic tube or tape reel packing 800/reel



Maximum Ratings and Electrical Characteristics (T_A = 25°C unless otherwise noted)

PARAMETER		TEST CONDITIONS		SYMBOL	VALUE	UNIT
Maximum Repetitive Peak Reverse Voltage				V _{RRM}	200	V
Working Peak Reverse Voltage				V _{RWM}	200	V
Maximum DC Blocking Voltage				V _{DC}	200	V
Maximum Average Forward Rectified Current at T _c =105°C	Total Device Per Diode			I _{F(AV)}	16 8	A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load per Diode				I _{FSM}	125	A
Voltage Rate of Change(rated V _R)				DV/dt	10000	V/us
Operating Junction Temperature Range				T _J	- 55 to+150	°C
Storage Temperature Range				T _{STG}	- 55 to+150	°C
Maximum Reverse Recover Time (I _F =0.5Amp, I _R =1.0Amp,I _{rec} =0.25Amp)				T _{rr}	35	ns
Maximum Instantaneous Forward Voltage per Leg		I _F =8A I _F =8A	T _C =25°C T _C =125°C	V _F	1.00 0.90	V
Maximum Reverse Current per Leg at Working Peak Reverse Voltage		T _J =25°C T _J =100°C		I _R	10 500	uA uA
Thermal Characteristics T _A =25°C unless otherwise noted						
Symbol	Parameter	TYP.(TO-263)				Unit
R _{θJC}	Thermal Resistance, Junction to Case per Leg	2.0				°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient per Leg	62.5				°C/W

Note: Pulse test:300us pulse width, duty cycle=2%

Ratings and Characteristics Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

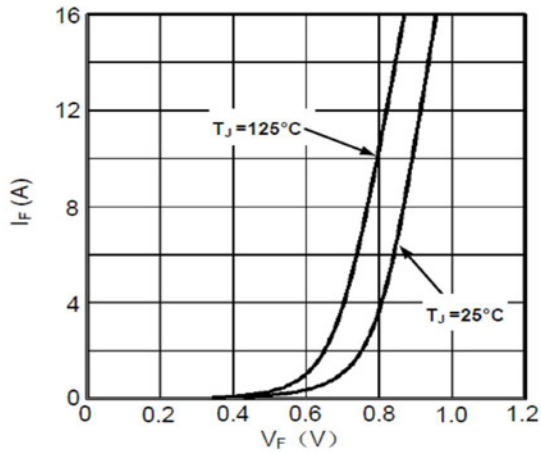


Fig1. Forward Voltage Drop vs Forward Current

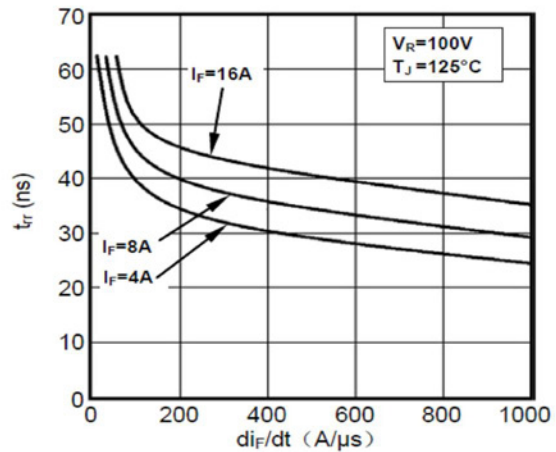


Fig2. Reverse Recovery Time vs di_F/dt

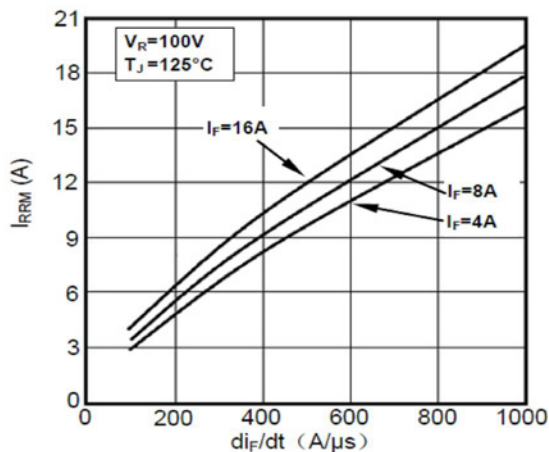


Fig3. Reverse Recovery Current vs di_F/dt

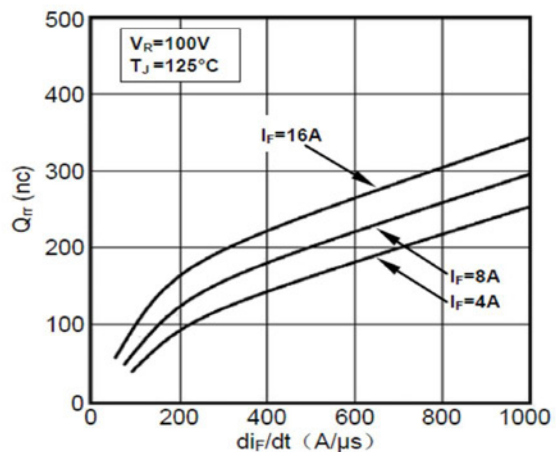


Fig4. Reverse Recovery Charge vs di_F/dt

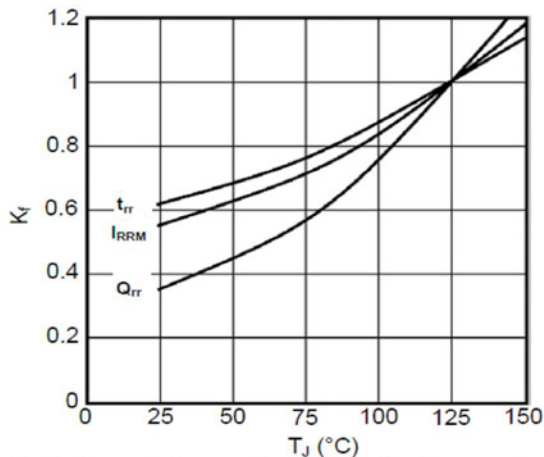


Fig5. Dynamic Parameters vs Junction Temperature

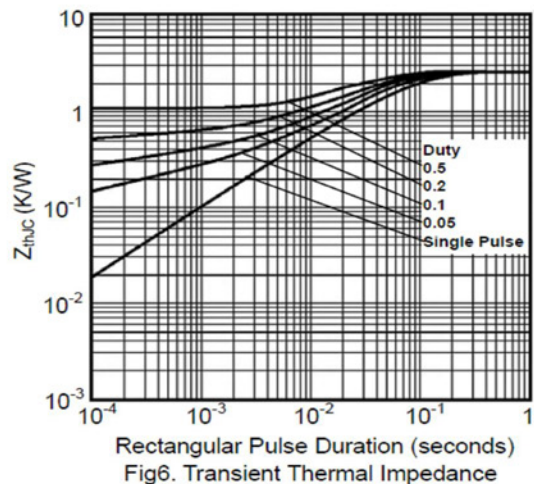
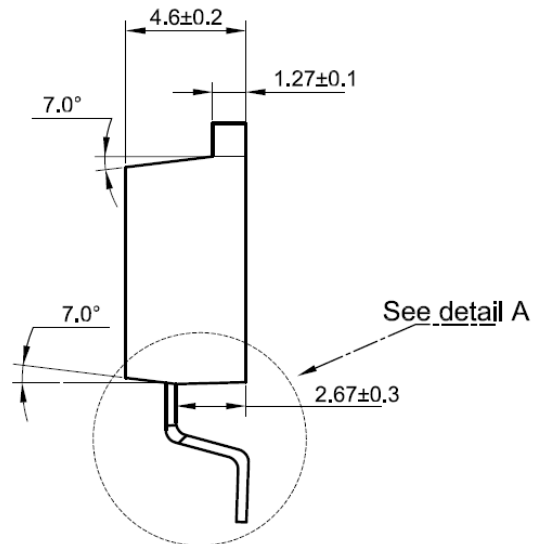
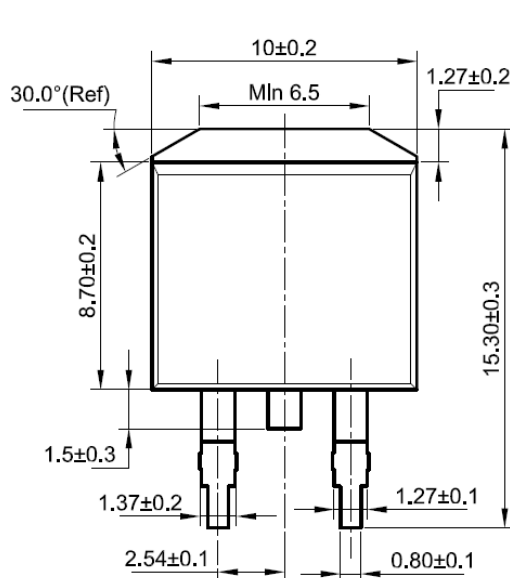


Fig6. Transient Thermal Impedance

Package Outline Dimensions

Unit: millimeters

TO-263



Detail A

